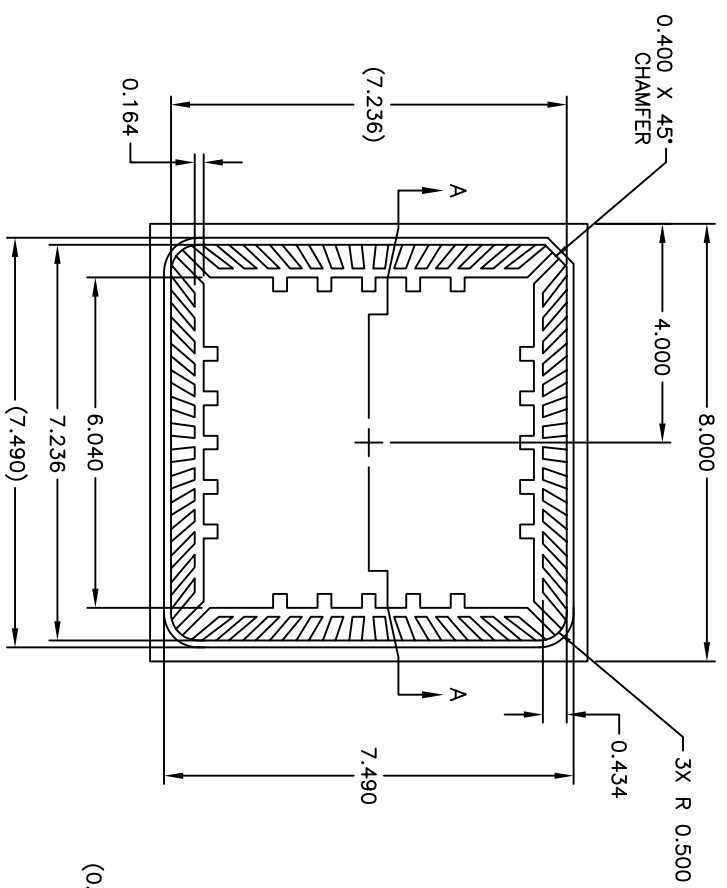
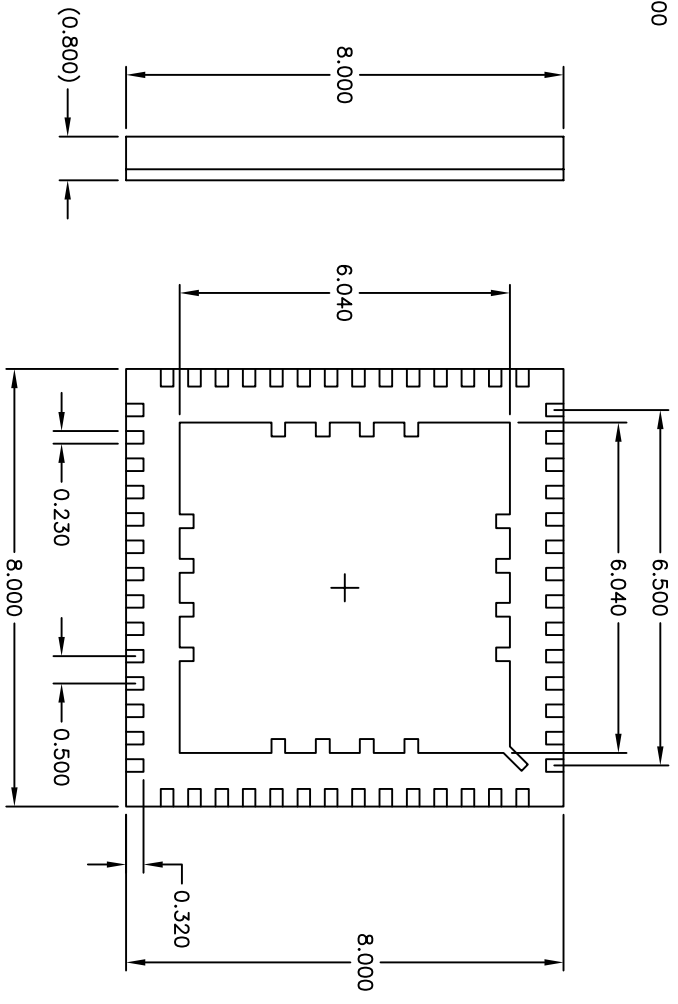


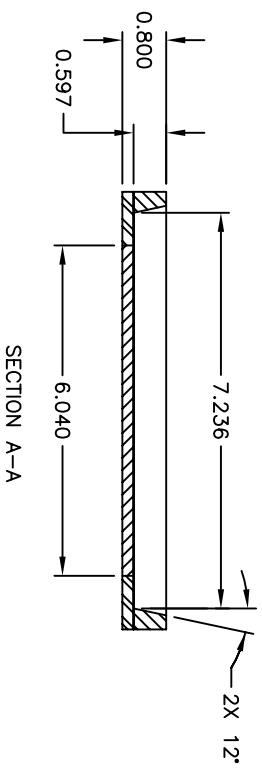
| REVISIONS | | | APPROVED |
|-----------|----------|--------------------|------------|
| EON NO. | DATE | DESCRIPTION | D.BENANDIO |
| 10503 | 10/27/05 | PRODUCTION RELEASE | |



TOP VIEW



BOTTOM VIEW



SECTION A-A

- NOTES:
1. BODY: PLASTIC, SEMICONDUCTOR GRADE.
 2. LEAD FRAME: COPPER, 194 FH.
 3. LEAD FINISH: FULL GOLD PLATE.
 4. FRAME THICKNESS: 0.2030 ±.0076.
 5. DIE PAD: 6.040 X 6.040.
 6. JEDEC OUTLINE: MO-220 (VLLD-5).

THIRD ANGLE PROJECTION

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS

TOLERANCES ARE: X.XXX ± 0.15 X.XXXX ± 0.010 ANGLES: ± 1'

DO NOT SCALE DRAWING

DRAWN BY: W. GRIFFITTS

CHECKED BY: P. FLASKERUD

DATE: 10/26/05

DATE: 10/26/05

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56 Lead 8mm x 8mm
 MLP Open-Pak

SIZE: A PART NO.: MLP8X8-56-OP-01
 SCALE: NONE FILE: MLP8X8-56-OP-01-R3.DWG

REV 3 SHEET 1 OF 1